

SOT1980-1

WLCSP36, wafer level chip scale package, 36 terminals, 1.63 mm x 1.53 mm x 0.225 mm body

26 October 2018

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP36
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	16-10-2018
Manufacturer package code	98ASA01262D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	1.63	-	mm
package width	-	1.53	-	mm
package height	-	0.225	-	mm
actual quantity of termination	-	36	-	



2 Package outline

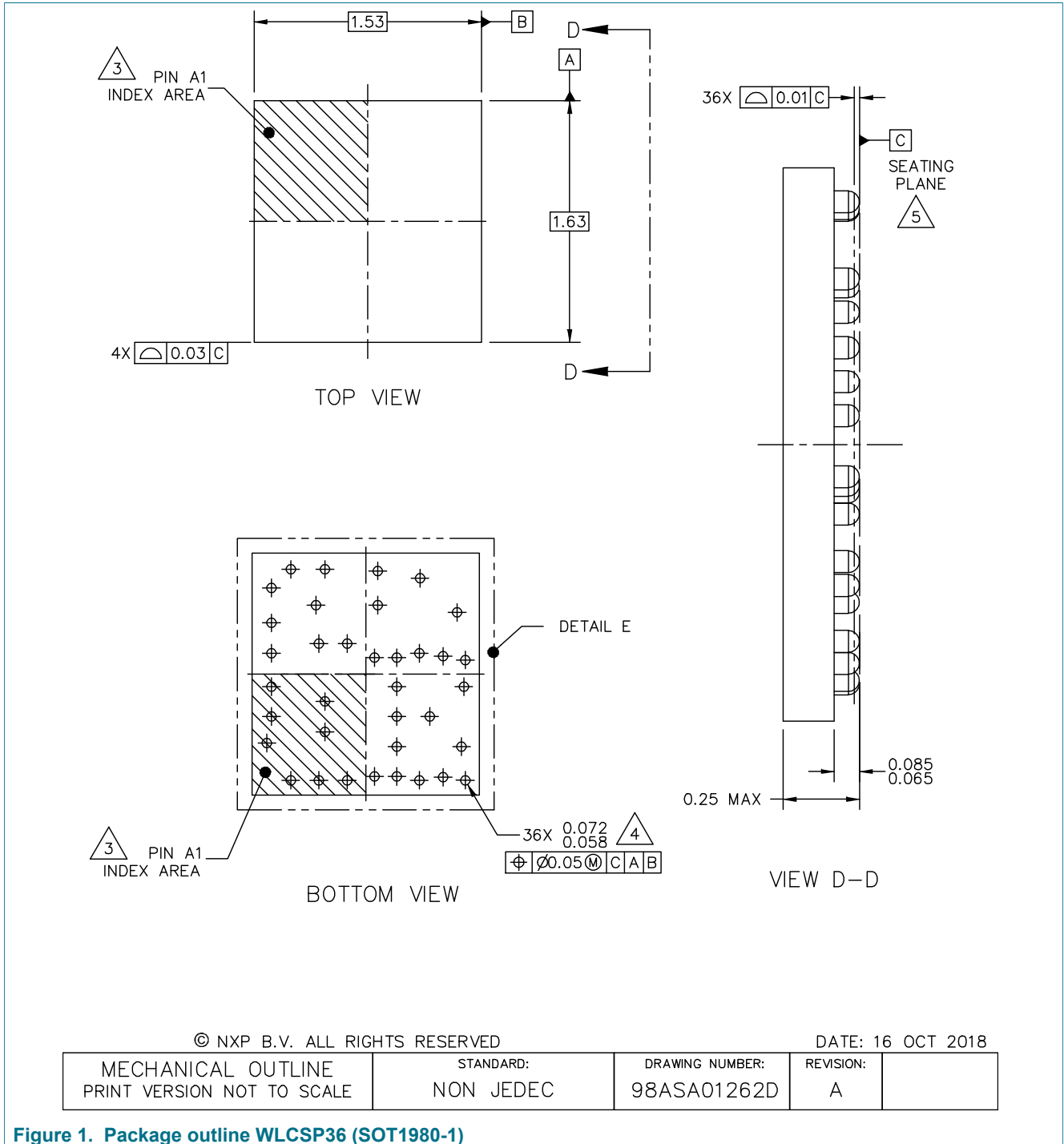


Figure 1. Package outline WLCSP36 (SOT1980-1)

WLCSP36, wafer level chip scale package, 36 terminals, 1.63 mm x 1.53 mm x 0.225 mm body

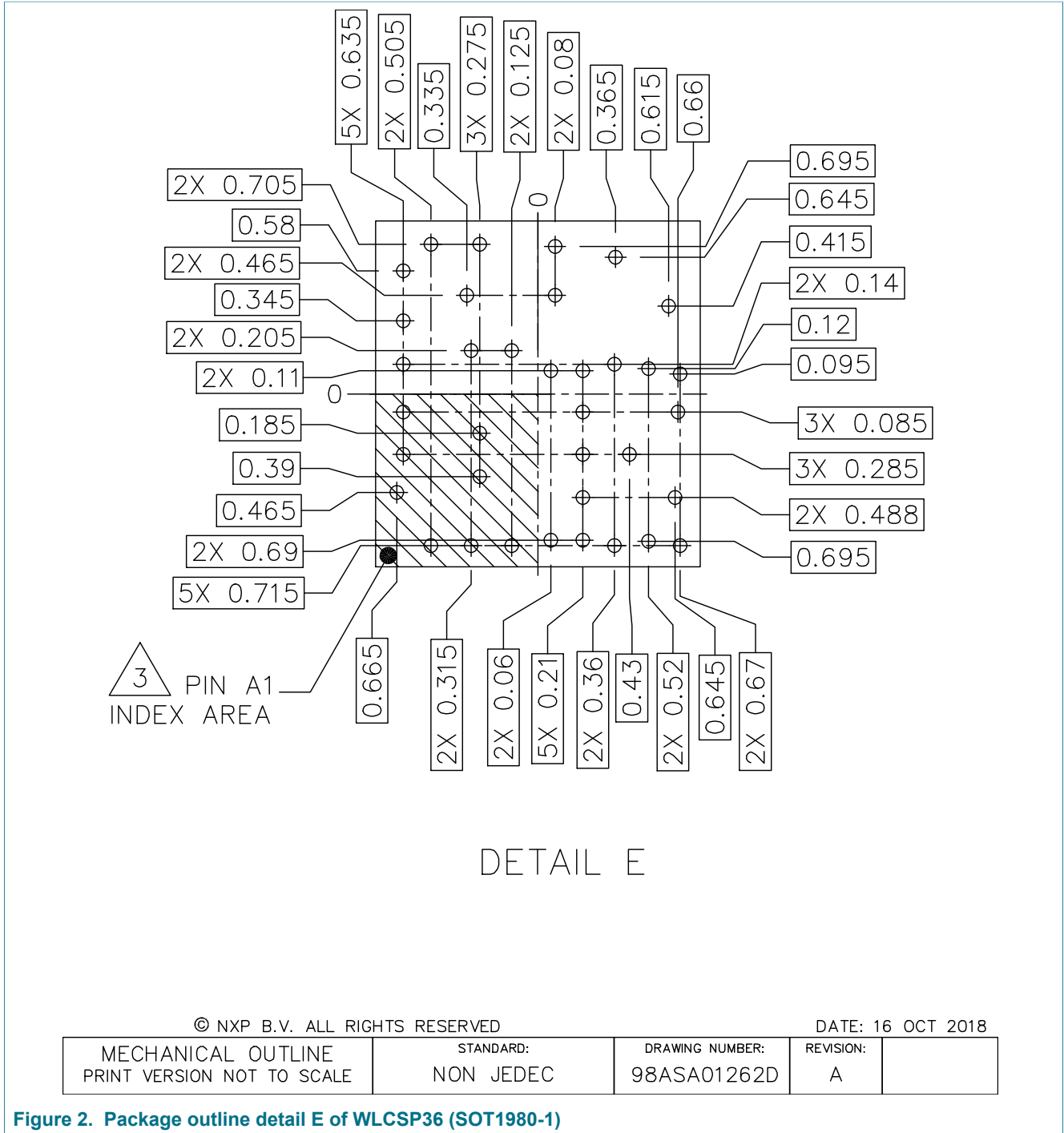
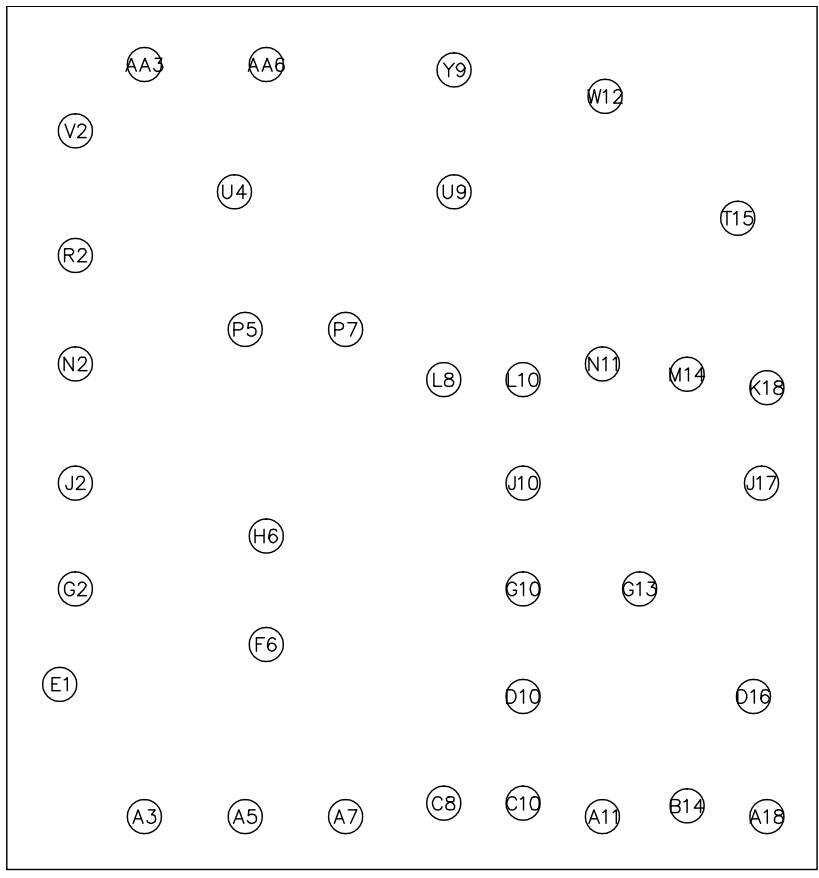


Figure 2. Package outline detail E of WLCSP36 (SOT1980-1)

WLCSP36, wafer level chip scale package, 36 terminals, 1.63 mm x 1.53 mm x 0.225 mm body



PIN NUMBERS
(VIEWED FROM BOTTOM, SAME AS DETAIL E)

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Figure 3. Package outline pin numbers of WLCSP36 (SOT1980-1)

WLCSP36, wafer level chip scale package, 36 terminals, 1.63 mm x 1.53 mm x 0.225 mm body

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

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Figure 4. Package outline note WLCSP36 (SOT1980-1)

3 Legal information

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Contents

1 Package summary1
2 Package outline2
3 Legal information6